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## ISTFA 2002: proceedings of the 28th International Symposium for Testing and Failure Analysis, 3-7 November 2002, Phoenix Civic Center, Phoenix, Arizona

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## **Abstrak**

## Contents:

- IPFA 2002 Best Paper Award Winner
- SEM/SThM-Hybrid-System: A New Tool for Advanced Thermal Analysis of Electronic Devices
- From Microns to Molecules—Can FA Remain Viable Through the Next Decade?
- Soft Defect Localization (SDL) on ICs
- Fault Localization and Functional Testing of ICs by Lock-in Thermography
- Visualisation of Electrically Active Areas Using Electron Holography
- A Study of Photoelectron Emission Microscopy Contrast Mechanisms Relevant to Microelectronics
- Application of Acoustic Fourier Domain Imaging for the Evaluation of Advanced Micro Electronic Packages
- Orientation Imaging Microscopy Applications in Cu-Interconnects and Cu-Cu Wire Bonding
- Materials Analysis and Process Monitoring in MegaFabs
- STEM (Scanning Transmission Electron Microscopy) in a SEM (Scanning Electron Microscope) for Failure Analysis and Metrology
- Microcalorimeter Energy Dispersive X-Ray Spectroscopy in Routine Semiconductor Failure Analysis
- A Working Method for Adapting the (SEM) Scanning Electron Microscope to Produce (STEM) Scanning Transmission Electron Microscope Images
- Applications of EELS to Semiconductor Devices Failure Analysis by Using a 300 keV TEM
- Laser Milling Methods for Package Failure Analysis
- Laser Decapsulation of Transfer Molded Plastic Packages for Failure Analysis
- Investigation of Microstructure Change on Ni-based UBM Systems in Lead Free Solder
- Failure Analysis Strategy For 2 Stacked Die CSP
- Evaluation of Package Defects by Thermal Imaging Techniques
- Backside Hot Spot Detection
- Optimizing Backside Image Quality
- Infrared Microthermography for Integrated Circuit Fault Location; Sensitivity and Limitations
- Failure Analysis of Tungsten Contact Failure in a 0.13 um CMOS Process

- Backside Photoemission and Infrared Microthermography for Rapid Debug of Compound Semiconductor Devices
- Laser-Voltage-Prober Measurements on Bipolar Devices
- Application of Focused Ion Beam in Debug and Characterization of  $0.13~\mathrm{um}$  Copper Interconnect Technology
- Thin-Die Flip Chip Physical-FA Process Flow
- Failure Mechanism and Rootcause Analysis of UBGA Solder Ball Contamination
- Passivation Damage and Residue-Induced Package Failure Analysis For a 16
  Lead SOIC GaAs RF/IF Package
- Study on a Single NFET Degradation After Circuit Modification with FIB
- New Techniques to Improve the Efficiency of TEM Sample Preparation
- A Transmission X-Ray Microscope (TXM) for Non-Destructive 3D Imaging of ICs at Sub-100 nm Resolution
- A Broadband Model for Ultrasonic Pulses in the Presence of Thin Layers in Microelectronics
- Beam-Based Localization Techniques for 0.18 um IC Failure Analysis after Reliability Test
- Methodologies for Isolating Faults in Multi Chip Fiber Optic Transceivers that Use GHz Mixed Signal ICs
- Application of Various Fault Localization Techniques to Different Types of 6T-SRAM column Failures
- Missing Metal Pillar Failure Analysis-A Plug Technology Issue
- Reliability and failure analysis of RF MEMS switches
- Failure Analysis of Polysilicon Micromirror Arrays
- Failure Analysis of the Digital Micromirror Device
- Wavefront Coded Imaging Systems for MEMS Analysis
- Sample preparation for Vertical Transistors in DRAM
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- CMOS Backside Deprocessing With TMAH/IPA as a Sample Preparation Procedure for Failure Analysis
- Investigation of Choline Hydroxide for Selective Silicon Etch from a Gate Oxide Failure Analysis Standpoint
- In situ Decapsulation of Plastic Encapsulated Devices Mounted to a Printed Circuit Board
- A Standardized Scientific Method Formulation for Failure Analysis Application
- Probeless FA Approach: a Breakthrough Simulation Based Failure Analysis Method
- Electrical Faults Captured by In-Line E-beam Inspection and Failure Analysis
- Effect of Corner Underfill Voids on Chip Scale Package (CSP) Performance Under Mechanical Loading
- Leakage Isolation of Mixed-Signal Devices at Operating Modes

- Method for Measuring Package to Board Interconnection Shear Strength for Area Array, Fine Pitch Packages
- Picosecond Imaging Circuit Analysis of Leakage Currents in CMOS Circuits
- Scanning SQUID Microscopy for Die Level Fault Isolation
- A Successful Failure Localization Approach for Defect Identification on High Resistance Interconnects
- Backside FIB Device Modifications Through the BOX Layer of an SOI Device
- Coax